

IN THE CLAIMS

This listing of claims replaces all prior versions and listings of claims in the application.

13. (Previously presented) A method for growing a gallium nitride based semiconductor material overlying a substrate of a dissimilar material, comprising:

forming a first gallium nitride based semiconductor layer overlying said substrate, said first gallium nitride based semiconductor layer having defects due to a lattice mis-match between said substrate and said first gallium nitride based semiconductor layer;

forming a trench in said first gallium nitride based semiconductor layer, said trench having a bottom surface and side walls;

depositing a first material on a surface of said first gallium nitride based semiconductor layer to prevent a second gallium nitride based semiconductor layer from nucleating on said surface of said first gallium nitride based semiconductor layer; and

growing said second gallium nitride based semiconductor layer, of a material different from said first gallium nitride based semiconductor layer, extending from at least one of said side walls, a bottom surface of said trench being of a material such that said second gallium nitride based semiconductor layer will not nucleate thereon, said second gallium nitride based semiconductor layer having fewer defects than said first gallium nitride based semiconductor layer.

14. (Previously presented) The method of claim 13 wherein at least one additional layer is formed between said first gallium nitride based semiconductor layer and said substrate.

15. (Previously presented) The method of claim 13 further comprising depositing a second material to prevent said second gallium nitride based semiconductor layer from growing on said bottom surface of said trench.

16. (Previously presented) The method of claim 15 wherein said second material is an electrical conductor.

17. (Previously presented) The method of claim 16 wherein said second material is titanium nitride.

18. (Previously presented) The method of claim 13 further comprising depositing material to prevent gallium nitride from growing on one of said side walls of said trench.

19. (Previously presented) The method of claim 13 wherein said forming a trench is conducted before said depositing.

20. (Previously presented) The method of claim 13 wherein said trench extends all the way through said first gallium nitride based semiconductor layer.

21. (Previously presented) The method of claim 13 wherein said first gallium nitride based semiconductor layer is aluminum gallium nitride and said second gallium nitride based semiconductor layer is gallium nitride.

22. (Previously presented) The method of claim 13 wherein said first material is silicon dioxide.

23. (Previously presented) The method of claim 13 wherein said first material is deposited on a top surface of said first gallium nitride based semiconductor layer.

24. (Previously presented) The method of claim 13 further comprising depositing additional layers overlying said second gallium nitride based semiconductor material, wherein at least one of said additional layers is a first cladding layer.

25. (Previously presented) The method of claim 24 wherein at least one of said additional layers is an active layer overlying said cladding layer.

26. (Previously presented) The method of claim 25 wherein at least one of said additional layers is a second cladding layer overlying said active layer.

27. (Previously presented) The method of claim 13 further comprising depositing

additional layers overlying said second gallium nitride based semiconductor material, wherein at least one of said additional layers is an active layer for emitting light.

28. (Previously presented) The method of claim 13 wherein said first material overlaps at least a portion of at least one of said side walls.

29-33 (Canceled.)

IN THE DRAWINGS

The attached sheet of drawings includes changes to Figures 1, and 2. The legend "Prior Art" has been added to each of the figures. The attached sheet, which include Figures 1, and 2, replaces the original sheet including the same figures.

Attachment: Replacement Sheet Page 1 of 4 (total of 1 sheet).

Attached at the end.